



MFR301™ Liquid Flux

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NO CLEAN, SUSTAINED ACTIVITY FLUX

Multicore MFR301 is a no clean, high activity liquid flux for surfaces with poor solderability from the pioneers of "no clean" technology.

- Lead free and tin-lead compatible
- Fast soldering on conventional leaded and SMD components – no bridges or icicles
- Exceptional through-hole penetration
- Sustained performance for maximum process window
- No cleaning – reduces costs
- Minimal residues to interfere with ATE probes without cleaning
- Compatible with rosin based surface preservatives
- Foam, spray or wave application

APPLICATIONS

Multicore MFR301 is recommended for consumer electronics and general electrical soldering applications. The activator package is similar to that previously deployed in R32-07i, but the acid value has been increased to further enhance efficacy, especially when soldering to poorly preserved substrates/components. A small amount of rosin is complemented by the solvent package to ensure optimum drainage characteristics at the exit of the wave, minimising bridges, spiking and mid-pad solder balling. This leaves a small amount of non-corrosive residue. MFR301 can be applied by any of the usual techniques: foam, spray or wave.

RECOMMENDED OPERATING CONDITIONS

The Printed Circuit Board: Multicore MFR301 is recommended for use on copper or tin-lead coated PCBs. It will solder satisfactorily over most rosin-based preservatives. It is recommended that the rosin based preservative be applied no longer than 3 months before soldering, since the period of protection is limited dependent on storage conditions.

Multicore MFR301 has been formulated to work over a wide range of solder resists.

Machine Preparation: When switching to Multicore MFR301 from any other flux, ensure all fingers, pallets and conveyors are thoroughly cleaned. It is recommended that Multicore MCF800 Cleaner is used in the finger cleaners.

Fluxing: Multicore MFR301 has been formulated for use in foam, spray or wave fluxers in the same way as ordinary fluxes on standard wave soldering machines. For foam fluxing it is important to remove excess flux from the circuit boards using the standard air knife or brushes supplied on the wave soldering machine. An air pressure of about 5-7 psi is recommended and the nozzle should be about 25mm below the board and angled back at a few degrees to the perpendicular to the plane of the board. This will ensure effective removal of excess flux without transferring droplets to the top of the following board. Sufficient space should be allowed between the foam fluxer and the air knife to prevent the air stream disturbing the foam.

Observing the following instructions will help ensure optimum foaming and soldering results.

1. Use **DRY AIR**.
2. Keep the flux tank **FULL** at all times.
3. The top of the foaming stone should be no more than 2cm below the surface of the liquid flux. A fine foaming stone is preferred and if necessary, raise the level of the stone.
4. The preferred width of the slot (opening) of the foam fluxer is 10mm. If it is wider and problems are encountered, add a strip of stainless steel or PVC across it to narrow the opening to 10mm. It is preferable to have a chimney for the foam which tapers towards the top.
5. **DO NOT** use hot fixtures or pallets as these cause the foam to deteriorate and increase losses by evaporation.
6. **DO NOT** use fixtures that have the potential to entrap flux.

Flux Control: Control of the flux concentration can be achieved in the conventional manner by measuring temperature and specific gravity. However, as the specific gravities of the flux and thinners are similar and will vary with water content, flux concentration control by measurement of acid value is more convenient and accurate.

Preheating: The optimum preheat temperature and time for a PCB depend on its design and the thermal mass of the components but the cycle should be sufficient to ensure that the flux coating is not visibly wet when it contacts the wave.

Conditions will vary from one machine to another but the following settings were found to give good results on a number of systems:

Conveyor Speed	Ft min ⁻¹	3	4	5
	m min ⁻¹	0.91	1.22	1.52
Topside Preheat	°C	80-85	85-90	95-100
	°F	176-185	185-194	203-212

It is advantageous to fit a topside canopy over the preheaters to produce more effective drying and activation. This will allow the use of faster conveyor speeds and improve soldering. At a speed of 1.5m min⁻¹, a contact length of 50-75mm between the wave and the PCB is recommended. At lower speeds, this contact length should be reduced. Very slow speeds through the solder wave may produce dull solder joints.

NOT FOR PRODUCT SPECIFICATIONS
THE TECHNICAL INFORMATION CONTAINED HEREIN IS INTENDED FOR REFERENCE ONLY. PLEASE CONTACT HENKEL TECHNOLOGIES TECHNICAL SERVICE FOR ASSISTANCE AND RECOMMENDATIONS ON SPECIFICATIONS FOR THIS PRODUCT.

IT IS IMPORTANT that flux solvent be removed by the preheat and that the PCB **IS NOT WET** when it reaches the solder wave.

Solders: Multicore MFR301 flux can be used with all solder alloys. The recommended maximum solder bath temperature is 270°C. The solder bath temperature can generally be reduced compared with processes using conventional fluxes. Temperatures as low as 235°C in tin-lead soldering and 245°C in lead free may be used in some situations and this results in improved soldering and less wastage through drossing. Dwell time on the wave should be 0.5-1.0 seconds (chip wave) and 2.0-3.0 seconds (laminar wave). Conveyor speed for dual wave systems should be at least 1.2 m min⁻¹.

To complete your no-clean assembly, use the compatible Multicore Cored Solder Wire and Solder Cream. Soldering iron tips should be kept clean with Multicore Tip Tinner/Cleaner TTC1 (data sheet available).

Cleaning: Special applications may have regulations insisting on board cleaning and in such cases Multicore MCF800 Cleaner may be used. Unlike water soluble fluxes, Multicore MFR301 flux is not corrosive towards PCB handling equipment.

TECHNICAL SPECIFICATION

The following table contains typical product data. A full description of test methods and detailed test results are available on request.

General Properties	MFR301
J-STD-004 classification	ROM0
EN 29454 classification	1.1.3
Colour	Pale rosin yellow
Smell	Alcoholic
Solids content	6 ± 0.5%
Acid value (on liquid) mg KOH/g	40 ± 1
Halide Content	zero
Specific gravity at 25°C (77°F)	0.802 ± 0.002
Flash point (Abel)	14°C
Thinners	PC70i

SPECIAL PROPERTIES

Surface Insulation Resistance

Multicore MFR301 passes the surface insulation resistance test requirements of J-STD-004 at 50V bias for 168h at 85°C and 85% RH.

Electromigration

Multicore MFR301 passes the electromigration test requirements of Telcordia (formerly known as Bellcore) GR-78-CORE at 10V bias for 500h at 65°C and 85% RH.

HEALTH AND SAFETY

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

Note

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, **Henkel Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel Corporation's products. Henkel Corporation specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits.** The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel Corporation patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.